

Result of tenders of RMB Sovereign Bonds held on August 2, 2023

The following is issued on behalf of the Hong Kong Monetary Authority:

Result of the tenders of RMB Sovereign Bonds held on August 2, 2023:

Tender Result

Tender Date : August 2, 2023

Bonds available for Tender : 5-year RMB Bonds

Issue Number : BCMKFB23019

Issue and Settlement Date : August 4, 2023

Maturity Date : August 4, 2028 (or the closest coupon payment date)

Application Amount : RMB 11,232 million

Issue Amount : RMB 3,000 million

Average accepted Coupon Rate : 2.44 per cent

Highest accepted Coupon Rate (Bonds' Coupon) : 2.52 per cent

Lowest accepted Coupon Rate : 1.80 per cent

Allocation Ratio : Approximately 65.22 per cent

Tender Result

Tender Date : August 2, 2023

Bonds available for Tender : 2-year RMB Bonds

Issue Number : BCMKFB23013 (Re-open)
Issue and Settlement Date : August 4, 2023
Maturity Date : June 16, 2025 (or the closest coupon payment date)
Coupon Rate : 2.20 per cent
Application Amount : RMB 18,560 million
Issue Amount : RMB 6,000 million
Average Accepted Price : 100.14
Lowest Accepted Price : 99.97
Highest Accepted Price : 101.10
Allocation Ratio : Approximately 68.75 per cent

Tender Result

Tender Date : August 2, 2023
Bonds available for Tender : 3-year RMB Bonds
Issue Number : BCMKFB23014 (Re-open)
Issue and Settlement Date : August 4, 2023
Maturity Date : June 16, 2026 (or the closest coupon payment date)
Coupon Rate : 2.30 per cent
Application Amount : RMB 12,622 million
Issue Amount : RMB 3,000 million
Average Accepted Price : 100.24

Lowest Accepted Price : 100.00

Highest Accepted Price : 101.96

Allocation Ratio : Approximately 38.18 per cent